



LOW Laser

The highly dynamic LOW laser depaneling machine is especially suitable for medium to high product volumes and meets growing requirements in the production process. Printed circuit boards of various materials are made using low-dust, low-stress laser sawing and milling techniques separated

with maximum product flexibility, precision and throughput. Highly dynamic linear motor axes, tools and grippers meet the highest quality standards and guarantee the depaneling machine a long service life and reliability.

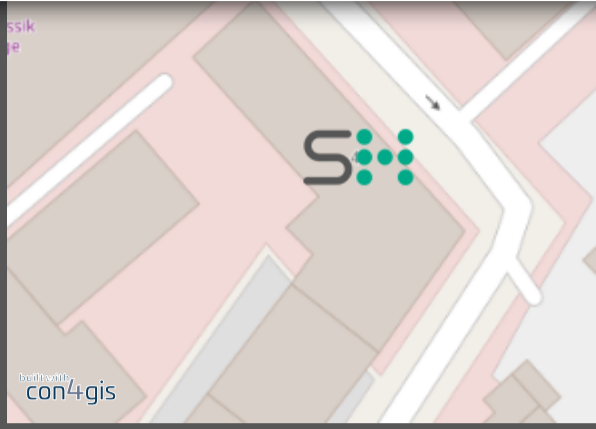
Product data

- Large work surface
- Rigid welded steel frame
- Highly dynamic linear motor axis
- Quick product change possible
- Flexible PCB mounting systems
- Cutting processes with discs, shaft tools and lasers
- Separates any PCB material
- Laser axis measurement
- Individual special sizes possible

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- Laser**
- Luftlager**
- Trennen**



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